

Keller and Heckman Announces: Tokyo Food Packaging Law Seminar

May 24, 2017 — Keller and Heckman will host its world-renowned Food Packaging Law Seminar for the first time in Tokyo, Japan, on November 14-15, 2017. Hailed as informative, useful, and “a must for anyone in the packaging field,” Keller and Heckman’s Food Packaging Law Seminars enable regulatory, scientific, and legal professionals to keep up-to-date on the latest global developments in food packaging laws and regulations.

The comprehensive seminar will cover both the basics on attaining clearances for food packaging materials in jurisdictions throughout the world and the latest developments, including changes brought about by the 7th amendment to the European Union’s Plastics Regulation and China’s most recent food packaging standards (announced in December 2016), as well as Japan’s expected adoption of a positive list system for food-contact materials. The seminar will also discuss the ramifications that may be expected from outside events such as legal challenges facing the U.S. Food and Drug Administration, and the UK’s exit from the European Union.

As with previous seminars, attendees will have the opportunity to talk one-on-one with Keller and Heckman’s internationally-recognized food packaging attorneys and scientists, and with other speakers, such as Masakazu Isurugi, Managing Director of Japan’s Hygienic PVC Association (JHPA).

Registration for the Tokyo Food Packaging Law Seminar is now open. Pricing and event details can be found [here](#).

[Keller and Heckman](#) has a broad practice in the areas of regulatory law, litigation, and business transactions, serving both domestic and international clients. With offices in Washington, D.C., Brussels, San Francisco, Shanghai, and Paris, the firm helps the world's most vital businesses achieve their objectives. A pioneer in the use of interdisciplinary approaches to problem-solving, Keller and Heckman has had an in-house scientific staff since 1971 that works closely with the firm's attorneys on matters of technical complexity.